LPM 2026 Session Chart

	JUNE 8 (Mon)	DAY-1: JUNE 9 (Tue)			DAY-2: JUNE 10 (Wed)				DAY-3: JUNE 11 (Thurs)			DAY-4: JUNE 12 (Fri)
		Room 1	Room 2	Room 3	Room 1	Room 2	Room 3	Crepe Myrtle Room	Room 1	Room 2	Room 3	Ballroom
8:30		Welcome Opening Remark (Ballroom)			Glass, ceramic, and other transparent materials processing I	3D printing and additive manufacturing I	Modeling, simulation, and AI approaches for laser- material interactions		Micro/nano-machining and fabrication I	Surface modification	Surface micro/nano structuring I	Closing Plenary 1: Norman Hodgson, Industrial UV Lasers – State-of-the-Art, Applications, Market, and Outlook
8:40												
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9:20		Plenary talk 1: Dustin Froula, A future of inertial confinement fusion without laser-plasma instabilities										
9:30												
9:40												Closing Plenary 2: Jiwang Yan, From Machining Waste to Functional Materials: Laser-Based Approaches toward Closed-Loop Manufacturing
9:50												
10:00												
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10:20		Plenary talk 2, Michael Schmidt, Beam shaping and production technology – a bidirectional relationship			COFFEE BREAK				COFFEE BREAK			
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10:40												Closing Plenary 3: Roberto Osellame, Femtosecond laser micromachining of transparent materials for advanced devices
10:50												
11:00												
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11:20		Plenary talk 3: Peter Kazansky, Recent advances in ultrafast laser nanostructuring of transparent materials: From Fundamentals to Applications			Glass, ceramic, and other transparent materials processing II	3D printing and additive manufacturing II	Sensing and diagnostics		Micro/nano-machining and fabrication II	Fundamentals of laser-materials interaction	Surface micro/nano structuring II	Awards and Closing
11:30												
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11:50		All Attendee Group Photo										
12:00												
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12:20		LUNCH BREAK			LUNCH BREAK			Women in Photonics and Laser Manufacturing Luncheon	LUNCH BREAK			
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13:50		Microprocessing of silicon and silicon carbide I	Laser drilling, cutting, and forming I	Laser processing for battery, fuel-cell, electrolyzer, fusion energy, and other energy devices	Laser-based direct writing I	3D printing and additive manufacturing III	Micro-welding and micro-bonding I		Micro/nano-machining and fabrication III	Novel Systems and Processes	Surface micro/nano structuring III	
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15:10		COFFEE BREAK			COFFEE BREAK				COFFEE BREAK			
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15:40		Microprocessing of silicon and sllicon carbide II	Laser drilling, cutting, and forming II	Post deadline: novel laser processing technologies	Laser-based direct writing II	Laser synthesis and processing of functional nanomaterials and 3D printing	Micro-welding and micro-bonding II		Micro/nano-machining and fabrication IV	Beam shaping	Laser Processing in Defense Applications	
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18:10									Poster / Exhibition / Networking Event (Ballroom)			
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19:20	Welcom Reception at Hyatt (Ballroom)				Banquet (Balloom)							
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